

ABSTRACT

Provided is a method of manufacturing an electronic component device, including: a step A of preparing a laminate
5 with an electronic component mounted on a body to be mounted;
a step B of preparing a sealing sheet; a step C of arranging
the sealing sheet on a heating plate and arranging the laminate
on the sealing sheet with a surface on which the electronic
component is mounted facing downward; and a step D of performing
10 hot press to embed the electronic component into the sealing
sheet after the step C.